


Substitute form 1449A/PTO				Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)				Application Number	not yet assigned
				Filing Date	concurrently herewith
				First Named Inventor	Jong-Rong Jan et al;
				Group Art Unit	not yet assigned
				Examiner Name	not yet assigned
Sheet	1	of	1	Attorney Docket Number	9180-30

U.S. PATENTS AND PATENT PUBLICATIONS					
Examiner Initials*	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code (if known)		
CAL	1.	US-3,625,837		Nelson et al;	12/07/1971
	2.	US-5,130,275		Dion	07/14/1992
	3.	US-5,211,807		Yee	05/18/1993
	4.	US-5,462,638		Datta et al;	10/31/1995
	5.	US-5,470,787		Greer	11/28/1995
	6.	US-5,471,092		Chan et al;	11/28/1995
	7.	US-5,759,437		Datta et al;	06/02/1998
	8.	US-5,796,168		Datta et al;	08/18/1998
	9.	US-5,937,320		Andricacos et al;	08/10/1999
	10.	US-6,015,505		David et al;	01/18/2000
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	12.	US-6,332,988		Berger, Jr. et al;	12/25/2001
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FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Office	Number	Kind Code (if known)		

OTHER NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published		
CAL	13.	R.B. Danzl and Allen McLaurin; "The Use of Concentrated Hydrogen Peroxide for the Removal of a TiW ARC from Aluminum Bond Pads" IEEE/CPMT Int'l Electronics Manufacturing Technology Symposium (1997) pp 99-104.		
CAL	14.	Akira Furuya and Yoshio Ohshita; "Ti concentration effect on adhesive energy at Cu/TiW interface"; Journal of Applied Physics, Vol. 84, No. 9, (Nov 1998) pp 4941-4944.		
CAL	15.	Julia Hawley and Van-Vo; "Solutions to Catastrophic Yield Problems in MCM-D Interconnect Production"; 1998 International Conference on Multichip Modules and High Density Packaging; pp 118-123.		

Examiner Signature		Date Considered	7/25/05
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.